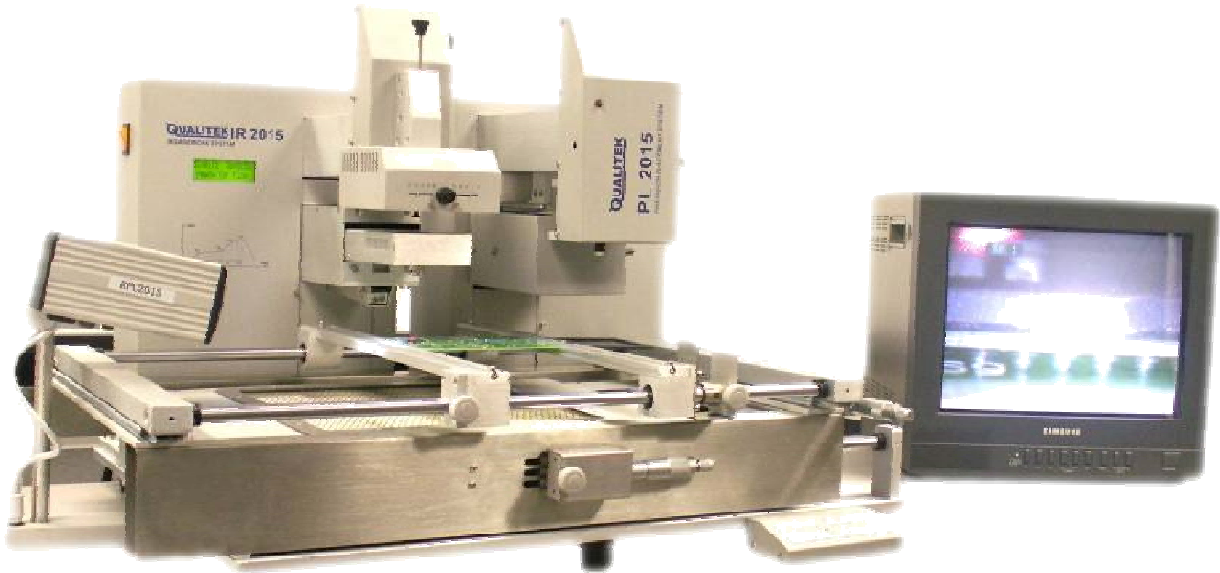


# QUALITEK BGA2015 REWORK SYSTEM



BGA rework system uses micro-processor control and infrared sensor technology to do soldering and desoldering to surface mounted components safely and accurately. It consists of QUALITEK IR2015 Infrared Rework System and QUALITEK PL2015 Precision Placement System.

\*The soldering and desoldering process are both under the monitoring of non-contact infrared sensor to get the optimum and reproductive PCB temperature

\*The technology of controlling reflow soldering by looped circuit ensures precise temperature window, even heat distribution and suitable peak value of temperature.

\*The adjustable aperture can protect the adjacent components (which is sensitive to the temperature) on PCB from being heated. No need for nozzles.

\*The use of reflow process camera supplies the critical message to judge the melting situation of solder materials during the whole soldering and desoldering process.

\*It can deal with PCB with big thermal capacity and other high temperature situation easily (For example, lead-free soldering).

## **Main Parts:**

### 1. IR 2015 Infrared Reflow Soldering Section

Infrared temperature sensor monitors BGA surface temperature to ensure precise temperature

technical window. Even heat distribution, real closed-loop control.

## 2. IRsoft Software

By means of PC, the whole process can be recorded, controlled and analyzed and then generate the curve diagram to meet the demands of modern electronic industry.

## 3. PL2015 Precision Aligning and Placing system

Visible double-color optical alignment. Accurate alignment and overlap between solder ball and soldering pad; Easy to control and place components

## 4. RPC2015 Reflow Camera

The melting course of BGA solder ball can be observed from different angles which provides critical information to get accurate and reliable process curve.

### **QUALITEK 2015 Specifications:**

IR Infrared Rework System:

General Power	3000W(MAX)
Power of Bottom Heater	500w*4=2000w or 400w*4=1600w(High Infrared heating tube/Dark Infrared heater optional)
Power of Top Heater	180w*4=720w(Infrared heating tube, wavelength about 2~8 $\mu$ m)
Size of Top Heater	60*60mm
Size of Bottom Heater	267*280mm
Adjusting Range of Top Heater	20~60mm(X、 Y direction both adjustable)
Vacuum Pump	12V/300mA, 0.05 Mpa (max)
Top Cooling Fan	12V/300mA 15CFM
Laser Alignment Tube	3V/30mA
Moveable Motor	24VDC/100mA
Moveable Arm Range	93mm
Max PCB Size	420*500mm
LCD Display Window	65.7*23.5mm 16*2 alphabet
Communication	RS-232C (connect with PC)

Infrared Temperature Sensor	0~300°C (Testing Range)
Outside K type Sensor	Optional

PL Precision Placement System:

Power	About 15W
Camera	22*10 times magnifying; 12V/300mA; Horizontal resolution: 480 lines; PLA format
Size of BGA to be aligned	60mm*60mm
LED Lighting	White LED (lower side), Red LED (upper side) (brightness adjustable)
Vacuum Pump	12V/600mA 0.05Mpa(max)
Camera Output Signal	Video Signal
Weight	22Kg

RPC Reflow Soldering Process Camera:

Power	About 15w
Camera	22*10 times magnifying; 12V/300Ma; Horizontal resolution: 480 TV lines; PAL format
LED Lighting	White LED (brightness adjustable)

**NOTE:**

Without additional notice if above parameters change.